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Data Sheet

October 2013

# N-Channel Logic Level Power MOSFET 50 V, 14 A, 100 $m\Omega$

These are N-channel power MOSFETs manufactured using the MegaFET process. This process, which uses feature sizes approaching those of LSI integrated circuits, gives optimum utilization of silicon, resulting in outstanding performance. They were designed for use in applications such as switching regulators, switching converters, motor drivers and relay drivers. This performance is accomplished through a special gate oxide design which provides full rated conductance at gate bias in the 3V-5V range, thereby facilitating true on-off power control directly from logic level (5V) integrated circuits.

Formerly developmental type TA09870.

# Ordering Information

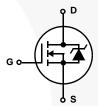
PART NUMBER	PACKAGE	BRAND
RFD14N05L	TO-251AA	14N05L
RFD14N05LSM	TO-252AA	14N05L
RFD14N05LSM9A	TO-252AA	14N05L

NOTE: When ordering, use the entire part number. Add the suffix 9A to obtain the TO-252AA variant in the tape and reel, i.e., RFD14N05LSM9A.

#### **Features**

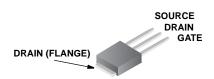
- 14A, 50V
- $r_{DS(ON)} = 0.100\Omega$
- Temperature Compensating PSPICE<sup>®</sup> Model
- Can be Driven Directly from CMOS, NMOS, and TTL Circuits
- · Peak Current vs Pulse Width Curve
- UIS Rating Curve
- 175°C Operating Temperature
- · Related Literature
  - TB334 "Guidelines for Soldering Surface Mount Components to PC Boards"

# Symbol



# Packaging

JEDEC TO-251AA



JEDEC TO-252AA



# RFD14N05L, RFD14N05LSM

# **Absolute Maximum Ratings** $T_C = 25^{\circ}C$ , Unless Otherwise Specified

	RFD14N05L, RFD14N05LSM,	
	RFD14N05LSM9A	UNITS
Drain to Source Voltage (Note 1)V <sub>DSS</sub>	50	V
Drain to Gate Voltage ( $R_{GS} = 20k\Omega$ ) (Note 1)	50	V
Gate to Source Voltage	±10	V
Continuous Drain Current	14	Α
Pulsed Drain Current (Note 3)	Refer to Peak Current Curve	
Pulsed Avalanche RatingE <sub>AS</sub>	Refer to UIS Curve	
Power Dissipation	48	W
Derate above 25°C	0.32	W/oC
Operating and Storage Temperature	-55 to 175	oC
Maximum Temperature for Soldering		
Leads at 0.063in (1.6mm) from Case for 10s	300	oC
Package Body for 10s, See Techbrief 334	260	οС

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

#### NOTE:

1.  $T_J = 25^{\circ}C$  to  $150^{\circ}C$ .

## **Electrical Specifications** $T_C = 25^{\circ}C$ , Unless Otherwise Specified

PARAMETER	SYMBOL	TEST C	ONDITIONS	MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	BV <sub>DSS</sub>	$I_D = 250 \mu A, V_{GS} = 0$	V, Figure 13	50	-	-	V
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}$ , $I_D = 250\mu A$ , Figure 12		1	-	2	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0	V	-	-	1	μΑ
		$V_{DS} = 40V, V_{GS} = 0V, T_{C} = 150^{\circ}C$		-	-	50	μΑ
Gate to Source Leakage Current	I <sub>GSS</sub>	$V_{GS} = \pm 10V$		-	-	±100	nA
Drain to Source On Resistance (Note 2)	r <sub>DS(ON)</sub>	$I_D = 14A, V_{GS} = 5V,$	Figures 9, 11	-	-	0.100	Ω
Turn-On Time	t <sub>(ON)</sub>	$V_{DD} = 25V, I_{D} = 7A,$ $R_{L} = 3.57\Omega, V_{GS} = 5V,$ $R_{GS} = 0.6\Omega$		-	-	60	ns
Turn-On Delay Time	t <sub>d</sub> (ON)			-	13	-	ns
Rise Time	t <sub>r</sub>			-	24	-	ns
Turn-Off Delay Time	t <sub>d</sub> (OFF)			-	42	-	ns
Fall Time	t <sub>f</sub>			-	16	-	ns
Turn-Off Time	t(OFF)			-	-	100	ns
Total Gate Charge	Q <sub>g(TOT)</sub>	$V_{GS} = 0V \text{ to } 10V$	$V_{DD} = 40V, I_D = 14A,$		-	40	nC
Gate Charge at 5V	Q <sub>g(5)</sub>	$V_{GS} = 0V \text{ to } 5V$	$R_L = 2.86\Omega$ Figures 20, 21	ı	-	25	nC
Threshold Gate Charge	Q <sub>g(TH)</sub>	$V_{GS} = 0V \text{ to } 1V$	Figures 20, 21		-	1.5	nC
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1MHz Figure 14			670	-	pF
Output Capacitance	Coss				185	-	pF
Reverse Transfer Capacitance	C <sub>RSS</sub>			-	50	-	pF
Thermal Resistance Junction to Case	$R_{ heta JC}$			-	-	3.125	oC/W
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	TO-251		-	- /	100	oC/W
	$R_{\theta JA}$	TO-252		-	-	100	oC/W

## **Source to Drain Diode Specifications**

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage (Note 2)	V <sub>SD</sub>	I <sub>SD</sub> = 14A	-	-	1.5	V
Diode Reverse Recovery Time	t <sub>rr</sub>	$I_{SD} = 14A$ , $dI_{SD}/dt = 100A/\mu s$	-	-	125	ns

#### NOTES:

- 2. Pulse Test: Pulse Width ≤300ms, Duty Cycle ≤2%.
- 3. Repetitive Rating: Pulse Width limited by max junction temperature. See Transient Thermal Impedance Curve (Figure 3) and Peak Current Capability Curve (Figure 5).

# Typical Performance Curves Unless Otherwise Specified

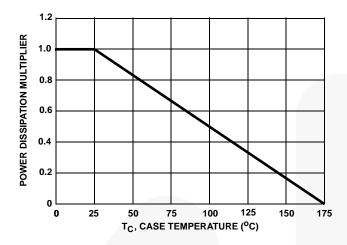


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs
TEMPERATURE

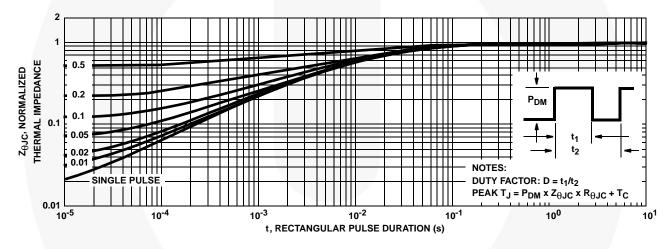


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

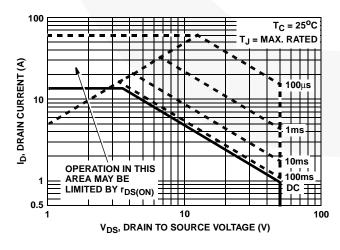


FIGURE 4. FORWARD BIAS SAFE OPERATING AREA

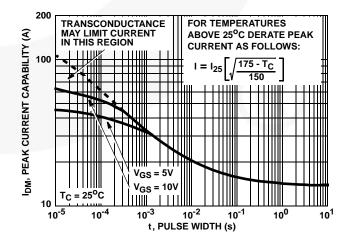
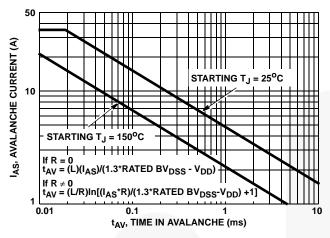


FIGURE 5. PEAK CURRENT CAPABILITY

### Typical Performance Curves Unless Otherwise Specified (Continued)



NOTE: Refer to Fairchild Application Notes AN9321 and AN9322.

FIGURE 6. UNCLAMPED INDUCTIVE SWITCHING

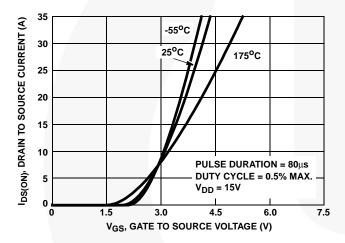


FIGURE 8. TRANSFER CHARACTERISTICS

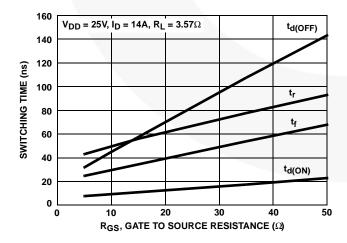


FIGURE 10. SWITCHING TIME vs GATE RESISTANCE

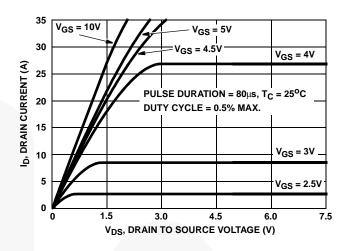


FIGURE 7. SATURATION CHARACTERISTICS

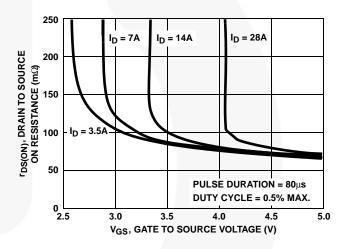


FIGURE 9. DRAIN TO SOURCE ON RESISTANCE vs GATE VOLTAGE AND DRAIN CURRENT

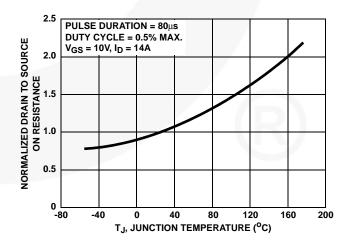


FIGURE 11. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

# Typical Performance Curves Unless Otherwise Specified (Continued)

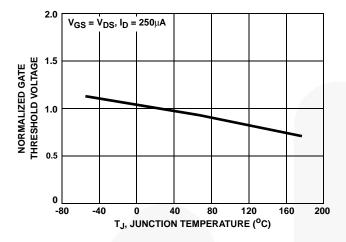


FIGURE 12. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

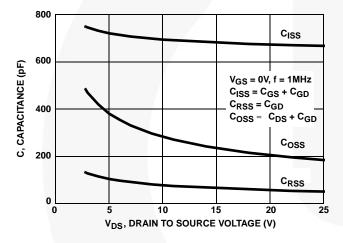


FIGURE 14. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE

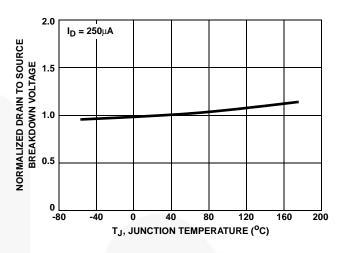
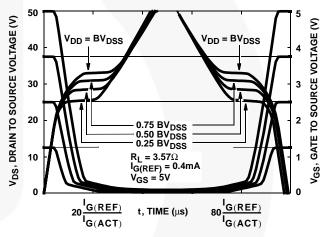


FIGURE 13. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE



NOTE: Refer to Fairchild Application Notes AN7254 and AN7260, FIGURE 15. TRANSCONDUCTANCE vs DRAIN CURRENT

BVDSS

# Test Circuits and Waveforms

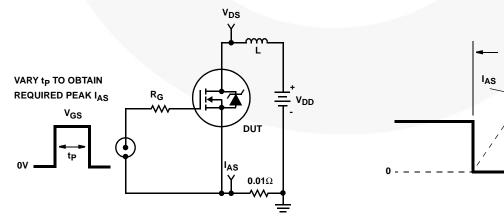


FIGURE 16. UNCLAMPED ENERGY TEST CIRCUIT

FIGURE 17. UNCLAMPED ENERGY WAVEFORMS

t<sub>AV</sub>

 $V_{DS}$ 

 $V_{DD}$ 

# Test Circuits and Waveforms (Continued)

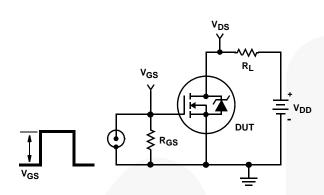


FIGURE 18. SWITCHING TIME TEST CIRCUIT

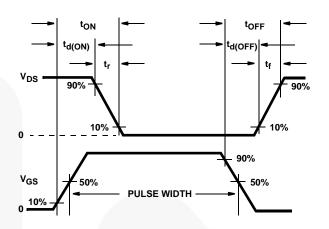


FIGURE 19. RESISTIVE SWITCHING WAVEFORMS

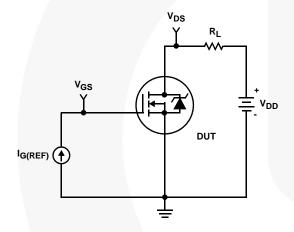


FIGURE 20. GATE CHARGE TEST CIRCUIT

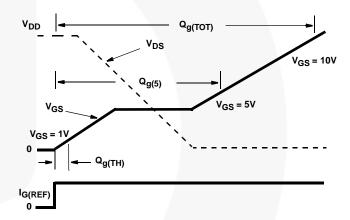


FIGURE 21. GATE CHARGE WAVEFORMS

#### **PSPICE Electrical Model**

.SUBCKT\_RFP14N05L\_2 1 3: rev 9/15/94 CA 12 8 1.464e-9 CB 15 14 1.64e-9 **DPLCAP** CIN 6 8 6.17e-10 DRAIN 10 LDRAIN DBODY 7 5 DBDMOD DBREAK 5 11 DBKMOD RSCL1 DPLCAP 10 5 DPLCAPMOD DBREAK RSCL2 **ESCL** EBREAK 11 7 17 18 65.35 EDS 14 8 5 8 1 50 EGS 13 8 6 8 1 DBODY RDRAIN **ESG** ESG 6 10 6 8 1 EBREAK (17) VTO + EVTO 20 6 18 8 1 MOS<sub>2</sub> EVTO GATE IT 8 17 1 20 MOS<sub>1</sub> LGATE RGATE LDRAIN 2 5 1e-9 RIN CIN LGATE 1 9 5.68e-9 **LSOURCE RSOURCE** LSOURCE 3 7 5.35e-9 8 3 SOURCE MOS1 16 6 8 8 MOSMOD M = 0.99 MOS2 16 21 8 8 MOSMOD M = 0.01 S2A S1A RBREAK 14 13 RBREAK 17 18 RBKMOD 1 18 13 RDRAIN 50 16 RDSMOD 33.1e-3 S1B S2B **RVTO** RGATE 9 20 5.85 RIN 6 8 1e9 19 CA CB  $^{(\!\!\!1\!\!\!)}$ RSCL1 5 51 RSCLMOD 1e-6 VBAT RSCL2 5 50 1e3 EGS EDS RSOURCE 8 7 RDSMOD 14.3e-3 RVTO 18 19 RVTOMOD 1 S1A 6 12 13 8 S1AMOD S1B 13 12 13 8 S1BMOD S2A 6 15 14 13 S2AMOD S2B 13 15 14 13 S2BMOD VBAT 8 19 DC 1 VTO 21 6 0.485 ESCL 51 50 VALUE =  $\{(V(5,51)/ABS(V(5,51)))*(PWR(V(5,51)*1e6/46,7))\}$ .MODEL DBDMOD D (IS = 2.23e-13 RS = 1.15e-2 TRS1 = 1.64e-3 TRS2 = 7.89e-6 CJO = 6.83e-10 TT = 3.68e-8) .MODEL DBKMOD D (RS = 3.8e-1 TRS1 = 1.89e-3 TRS2 = 1.13e-5) .MODEL DPLCAPMOD D (CJO = 25.7e-11 IS = 1e-30 N = 10) .MODEL MOSMOD NMOS (VTO = 1.935 KP = 18.89 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u) .MODEL RBKMOD RES (TC1 = 7.18e-4 TC2 = 1.53e-6) .MODEL RDSMOD RES (TC1 = 4.45e-3 TC2 = 2.9e-5) .MODEL RSCLMOD RES (TC1 = 2.8e-3 TC2 = 6.0e-6) .MODEL RVTOMOD RES (TC1 = -1.7e-3 TC2 = -2.0e-6) .MODEL S1AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -3.55 VOFF= -1.55) .MODEL S1BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -1.55 VOFF= -3.55) .MODEL S2AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -2.55 VOFF= 2.45) .MODEL S2BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = 2.45 VOFF= -2.55)

NOTE: For further discussion of the PSPICE model, consult **A New PSPICE Sub-circuit for the Power MOSFET Featuring Global Temperature Options**; authored by William J. Hepp and C. Frank Wheatley.

.ENDS



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